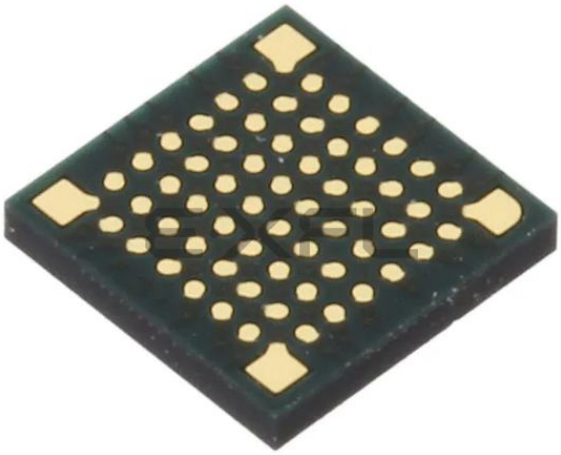

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	RX
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I²C, SCI, SPI
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	50
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 14x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-WFLGA
Supplier Device Package	64-FLGA (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f5110jadlf-u0

1.2 List of Products

Table 1.3 is a list of products, and Figure 1.1 shows how to read the product part no., memory capacity, and package type.

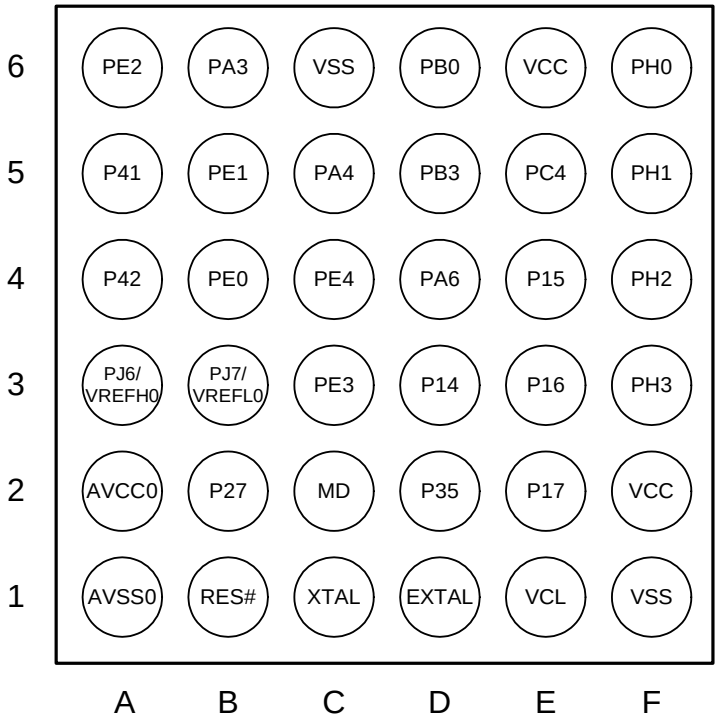
Table 1.3 List of Products (1/2)

Group	Part No.	Orderable Part No.	Package	ROM Capacity	RAM Capacity	Maximum Operating Frequency	Operating Temperature
RX110	R5F51105AGFM	R5F51105AGFM#30	PLQP0064KB-A	128 Kbytes	16 Kbytes	32 MHz	–40 to +105°C
	R5F51105AGFK	R5F51105AGFK#30	PLQP0064GA-A				
	R5F51105AGFL	R5F51105AGFL#30	PLQP0048KB-A				
	R5F51105AGNE	R5F51105AGNE#U0	PWQN0048KB-A				
	R5F51104AGFM	R5F51104AGFM#30	PLQP0064KB-A	96 Kbytes			
	R5F51104AGFK	R5F51104AGFK#30	PLQP0064GA-A				
	R5F51104AGFL	R5F51104AGFL#30	PLQP0048KB-A				
	R5F51104AGNE	R5F51104AGNE#U0	PWQN0048KB-A				
	R5F51103AGFM	R5F51103AGFM#30	PLQP0064KB-A	64 Kbytes	10 Kbytes		
	R5F51103AGFK	R5F51103AGFK#30	PLQP0064GA-A				
	R5F51103AGFL	R5F51103AGFL#30	PLQP0048KB-A				
	R5F51103AGNE	R5F51103AGNE#U0	PWQN0048KB-A				
	R5F51103AGNF	R5F51103AGNF#U0	PWQN0040KC-A				
	R5F51101AGFM	R5F51101AGFM#30	PLQP0064KB-A	32 Kbytes			
	R5F51101AGFK	R5F51101AGFK#30	PLQP0064GA-A				
	R5F51101AGFL	R5F51101AGFL#30	PLQP0048KB-A				
	R5F51101AGNE	R5F51101AGNE#U0	PWQN0048KB-A				
	R5F51101AGNF	R5F51101AGNF#U0	PWQN0040KC-A				
	R5F5110JAGFM	R5F5110JAGFM#30	PLQP0064KB-A	16 Kbytes	8 Kbytes		
	R5F5110JAGFK	R5F5110JAGFK#30	PLQP0064GA-A				
	R5F5110JAGFL	R5F5110JAGFL#30	PLQP0048KB-A				
	R5F5110JAGNE	R5F5110JAGNE#U0	PWQN0048KB-A				
	R5F5110JAGNF	R5F5110JAGNF#U0	PWQN0040KC-A				
	R5F5110HAGNF	R5F5110HAGNF#U0	PWQN0040KC-A	8 Kbytes			

Table 1.4 Pin Functions (2/3)

Classifications	Pin Name	I/O	Description
Serial communications interface (SCIe)	• Simple I2C mode		
	SSCL1, SSCL5	I/O	Input/output pins for the I2C clock.
	SSDA1, SSDA5	I/O	Input/output pins for the I2C data.
	• Simple SPI mode		
	SCK1, SCK5	I/O	Input/output pins for the clock.
	SMISO1, SMISO5	I/O	Input/output pins for slave transmit data.
	SMOSI1, SMOSI5	I/O	Input/output pins for master transmit data.
	SS1#, SS5#	Input	Chip-select input pins.
Serial communications interface (SCIf)	• Asynchronous mode/clock synchronous mode		
	SCK12	I/O	Input/output pin for the clock.
	RXD12	Input	Input pin for receiving data.
	TXD12	Output	Output pin for transmitting data.
	CTS12#	Input	Input pin for controlling the start of transmission and reception.
	RTS12#	Output	Output pin for controlling the start of transmission and reception.
	• Simple I2C mode		
	SSCL12	I/O	Input/output pin for the I2C clock.
	SSDA12	I/O	Input/output pin for the I2C data.
	• Simple SPI mode		
	SCK12	I/O	Input/output pin for the clock.
	SMISO12	I/O	Input/output pin for slave transmit data.
	SMOSI12	I/O	Input/output pin for master transmit data.
	SS12#	Input	Chip-select input pin.
	• Extended serial mode		
	RXDX12	Input	Input pin for data reception by SCIf.
	TXDX12	Output	Output pin for data transmission by SCIf.
	SIOX12	I/O	Input/output pin for data reception or transmission by SCIf.
I2C bus interface	SCL0	I/O	Input/output pin for I2C bus interface clocks. Bus can be directly driven by the N-channel open drain output.
	SDA0	I/O	Input/output pin for I2C bus interface data. Bus can be directly driven by the N-channel open drain output.
Serial peripheral interface	RSPCKA	I/O	Input/output pin for the RSPI clock.
	MOSIA	I/O	Input/output pin for transmitting data from the RSPI master.
	MISOA	I/O	Input/output pin for transmitting data from the RSPI slave.
	SSLA0	I/O	Input/output pin to select the slave for the RSPI.
	SSLA1 to SSLA3	Output	Output pins to select the slave for the RSPI.
12-bit A/D converter	AN000 to AN004, AN006, AN008 to AN015	Input	Input pins for the analog signals to be processed by the A/D converter.
	ADTRG0#	Input	Input pin for the external trigger signals that start the A/D conversion.
I/O ports	P03, P05	I/O	2-bit input/output pins.
	P14 to P17	I/O	4-bit input/output pins.
	P26, P27	I/O	2-bit input/output pins.
	P30 to P32, P35	I/O	4-bit input/output pins (P35 input pin).
	P40 to P44, P46	I/O	6-bit input/output pins.
	P54, P55	I/O	2-bit input/output pins.
	PA0, PA1, PA3, PA4, PA6	I/O	5-bit input/output pins.
	PB0, PB1, PB3, PB5 to PB7	I/O	6-bit input/output pins.

RX110 Group
PWLG0036KA-A
(36-pin WFLGA)
(Upper perspective view)



Note: This figure indicates the power supply pins and I/O port pins. For the pin configuration, see the table “List of Pins and Pin Functions (36-Pin WFLGA)”.
Note: For the position of A1 pin in the package, see “Package Dimensions”.

Figure 1.7 Pin Assignments of the 36-Pin WFLGA

Table 1.5 List of Pins and Pin Functions (64-Pin LFQFP/LQFP) (2/2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, RTC)	Communication (SCIe, SCIf, RSPI, RIIC)	Others
45		PA0		SSLA1	CACREF
46		PE5	MTIOC2B		IRQ5/AN013
47		PE4	MTIOC1A	MOSIA	IRQ4/AN012
48		PE3	MTIOC0A/MTIOC1B	CTS12#/RTS12#/SS12#/RSPCKA	IRQ3/AN011
49		PE2		RXD12/RXDX12/SMISO12/SSCL12	IRQ7/AN010
50		PE1		TXD12/TXDX12/SIOX12/SMOSI12/ SSDA12	IRQ1/AN009
51		PE0	MTIOC2A	SCK12	IRQ0/AN008
52		PE7			IRQ7/AN015
53		PE6			IRQ6/AN014
54		P46*1			AN006
55		P44*1			AN004
56		P43*1			AN003
57		P42*1			AN002
58		P41*1			AN001
59	VREFL0	PJ7*1			
60		P40*1			AN000
61	VREFH0	PJ6*1			
62	AVSS0				
63	AVCC0				
64		P05			

Note 1. The power source of the I/O buffer for these pins is AVCC0.

Table 1.7 List of Pins and Pin Functions (48-Pin LFQFP/HWQFN) (1/2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, RTC)	Communication (SCIe, SCIf, RSPI, RIIC)	Others
1		P27	MTIOC2B	SCK1/SCK12	IRQ3/CMPA2/ CACREF/ADTRG0#
2		P26	MTIOC2A	TXD1/SMOSI1/SSDA1	
3	MD				FINED
4	RES#				
5	XCOUT				
6	XCIN	PH7			
7		P35			NMI
8	XTAL				
9	EXTAL				
10	VCL				
11	VSS				
12	VCC				
13		P17	MTIOC0C	SCK1/MISOA/SDA0/RXD12/RXDX12/ SMISO12/SSCL12	IRQ7
14		P16	RTCOUT	TXD1/SMOSI1/SSDA1/MOSIA/SCL0	IRQ6/ADTRG0#
15		P15	MTIOC0B/MTCLKB	RXD1/SMISO1/SSCL1/RSPCKA	IRQ5/CLKOUT
16		P14	MTIOC0A/MTCLKA	CTS1#/RTS1#/SS1#/SSLA0/TXD12/ TXDX12/SIOX12/SMOSI12/SSDA12	IRQ4
17		PH3	MTIOC1A		
18		PH2			IRQ1
19		PH1			IRQ0
20		PH0	MTIOC1B		CACREF
21		PC7	MTCLKB	TXD1/SMOSI1/SSDA1/MISOA	CACREF
22		PC6	MTCLKA	RXD1/SMISO1/SSCL1/MOSIA	
23		PC5	MTCLKD	SCK1/RSPCKA	
24		PC4	MTCLKC	SCK5/SSLA0	IRQ2/CLKOUT
25		PB5/PC3	MTIOC2A/MTIOC1B		
26		PB3/PC2	MTIOC0A		
27		PB1/PC1	MTIOC0C		IRQ4
28	VCC				
29		PB0/PC0	MTIC5W/MTIOC0C/ RTCOUT	SCL0/RSPCKA	IRQ2/ADTRG0#
30	VSS				
31		PA6	MTIC5V/MTCLKB/MTIOC2A	CTS5#/RTS5#/SS5#/SDA0/MOSIA	IRQ3
32		PA4	MTIC5U/MTCLKA/MTIOC2B	TXD5/SMOSI5/SSDA5/SSLA0	IRQ5
33		PA3	MTIOC0D/MTCLKD/ MTIOC1B	RXD5/SMISO5/SSCL5/MISOA	IRQ6
34		PA1	MTIOC0B/MTCLKC/ RTCOUT	SCK5/SSLA2	
35		PE4	MTIOC1A	MOSIA	IRQ4/AN012
36		PE3	MTIOC0A/MTIOC1B	CTS12#/RTS12#/SS12#/RSPCKA	IRQ3/AN011
37		PE2		RXD12/RXDX12/SMISO12/SSCL12	IRQ7/AN010
38		PE1		TXD12/TXDX12/SIOX12/SMOSI12/ SSDA12	IRQ1/AN009
39		PE0	MTIOC2A	SCK12	IRQ0/AN008
40		PE7			IRQ7/AN015
41		P46*1			AN006
42		P42*1			AN002
43		P41*1			AN001
44	VREFL0	PJ7*1			

Table 1.7 List of Pins and Pin Functions (48-Pin LFQFP/HWQFN) (2/2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, RTC)	Communication (SCIe, SCIf, RSPI, RIIC)	Others
45		P40*1			AN000
46	VREFH0	PJ6*1			
47	AVSS0				
48	AVCC0				

Note 1. The power source of the I/O buffer for these pins is AVCC0.

2.1 General-Purpose Registers (R0 to R15)

This CPU has 16 general-purpose registers (R0 to R15). R0 to R15 can be used as data registers or address registers. R0, a general-purpose register, also functions as the stack pointer (SP). The stack pointer is switched to operate as the interrupt stack pointer (ISP) or user stack pointer (USP) by the value of the stack pointer select bit (U) in the processor status word (PSW).

2.2 Control Registers

(1) Interrupt Stack Pointer (ISP)/User Stack Pointer (USP)

The stack pointer (SP) can be either of two types, the interrupt stack pointer (ISP) or the user stack pointer (USP). Whether the stack pointer operates as the ISP or USP depends on the value of the stack pointer select bit (U) in the processor status word (PSW).
Set the ISP or USP to a multiple of 4, as this reduces the numbers of cycles required to execute interrupt sequences and instructions entailing stack manipulation.

(2) Interrupt Table Register (INTB)

The interrupt table register (INTB) specifies the address where the relocatable vector table starts.

(3) Program Counter (PC)

The program counter (PC) indicates the address of the instruction being executed.

(4) Processor Status Word (PSW)

The processor status word (PSW) indicates the results of instruction execution or the state of the CPU.

(5) Backup PC (BPC)

The backup PC (BPC) is provided to speed up response to interrupts.
After a fast interrupt has been generated, the contents of the program counter (PC) are saved in the BPC register.

(6) Backup PSW (BPSW)

The backup PSW (BPSW) is provided to speed up response to interrupts.
After a fast interrupt has been generated, the contents of the processor status word (PSW) are saved in the BPSW. The allocation of bits in the BPSW corresponds to that in the PSW.

(7) Fast Interrupt Vector Register (FINTV)

The fast interrupt vector register (FINTV) is provided to speed up response to interrupts.
The FINTV register specifies a branch destination address when a fast interrupt has been generated.

2.3 Register Associated with DSP Instructions

(1) Accumulator (ACC)

The accumulator (ACC) is a 64-bit register used for DSP instructions. The accumulator is also used for the multiply and multiply-and-accumulate instructions; EMUL, EMULU, MUL, and RMPA, in which case the prior value in the accumulator is modified by execution of the instruction.
Use the MVTACHI and MVTACLO instructions for writing to the accumulator. The MVTACHI and MVTACLO instructions write data to the higher-order 32 bits (bits 63 to 32) and the lower-order 32 bits (bits 31 to 0), respectively.
Use the MVFACHI and MVFACMI instructions for reading data from the accumulator. The MVFACHI and MVFACMI instructions read data from the higher-order 32 bits (bits 63 to 32) and the middle 32 bits (bits 47 to 16), respectively.

Table 4.1 List of I/O Registers (Address Order) (13/13)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
007F C0C0h	FLASH	Protection Unlock Register	FPR	8	8	2 or 3 FCLK
007F C0C1h	FLASH	Protection Unlock Status Register	FPSR	8	8	2 or 3 FCLK
007F C0C2h	FLASH	Flash Read Buffer Register L	FRBL	16	16	2 or 3 FCLK
007F C0C4h	FLASH	Flash Read Buffer Register H	FRBH	16	16	2 or 3 FCLK
007F FF80h	FLASH	Flash P/E Mode Control Register	FPMCR	8	8	2 or 3 FCLK
007F FF81h	FLASH	Flash Area Select Register	FASR	8	8	2 or 3 FCLK
007F FF82h	FLASH	Flash Processing Start Address Register L	FSARL	16	16	2 or 3 FCLK
007F FF84h	FLASH	Flash Processing Start Address Register H	FSARH	8	8	2 or 3 FCLK
007F FF85h	FLASH	Flash Control Register	FCR	8	8	2 or 3 FCLK
007F FF86h	FLASH	Flash Processing End Address Register L	FEARL	16	16	2 or 3 FCLK
007F FF88h	FLASH	Flash Processing End Address Register H	FEARH	8	8	2 or 3 FCLK
007F FF89h	FLASH	Flash Reset Register	FRESETR	8	8	2 or 3 FCLK
007F FF8Ah	FLASH	Flash Status Register 0	FSTATR0	8	8	2 or 3 FCLK
007F FF8Bh	FLASH	Flash Status Register 1	FSTATR1	8	8	2 or 3 FCLK
007F FF8Ch	FLASH	Flash Write Buffer Register L	FWBL	16	16	2 or 3 FCLK
007F FF8Eh	FLASH	Flash Write Buffer Register H	FWBH	16	16	2 or 3 FCLK
007F FFB2h	FLASH	Flash P/E Mode Entry Register	FENTRYR	16	16	2 or 3 FCLK

Note 1. Odd addresses cannot be accessed in 16-bit units. When accessing a register in 16-bit units, access the address of the TMOCNTL register. Table 24.6 lists register allocation for 16-bit access in the User's Manual: Hardware.

Table 5.17 Output Voltage (1)

Conditions: 2.7 V ≤ VCC ≤ 3.6 V, 2.7 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +10°C

Item			Symbol	Min.	Max.	Unit	Test Conditions
Low-level output voltage	All output ports (except for RIIC, ports P40 to P44, P46, ports PJ6, PJ7)		V_{OL}	—	0.6	V	I_{OL} = 3.0 mA
				—	0.4		I_{OL} = 1.5 mA
	Ports P40 to P44, P46, ports PJ6, PJ7			—	0.4		I_{OL} = 0.4 mA
	RIIC pins	Standard mode		—	0.4		I_{OL} = 3.0 mA
		Fast mode		—	0.6		I_{OL} = 6.0 mA
High-level output voltage	All output ports (except for ports P40 to P44, P46, ports PJ6, PJ7)		V_{OH}	VCC – 0.5	—	V	I_{OH} = –2.0 mA
	Ports P40 to P44, P46, ports PJ6, PJ7			AVCC0 – 0.5	—		I_{OH} = –0.1 mA

Table 5.18 Output Voltage (2)

Conditions: 1.8 V ≤ VCC ≤ 2.7 V, 1.8 V ≤ AVCC0 ≤ 2.7 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Max.	Unit	Test Conditions
Low-level output voltage	All output ports (except for ports P40 to P44, P46, ports PJ6, PJ7)	V_{OL}	—	0.6	V	I_{OL} = 1.5 mA
	Ports P40 to P44, P46, ports PJ6, PJ7		—	0.4		I_{OL} = 0.4 mA
High-level output voltage	All output ports (except for ports P40 to P44, P46, ports PJ6, PJ7)	V_{OH}	VCC – 0.5	—	V	I_{OH} = –1.0 mA
	Ports P40 to P44, P46, ports PJ6, PJ7		AVCC0 – 0.5	—		I_{OH} = –0.1 mA

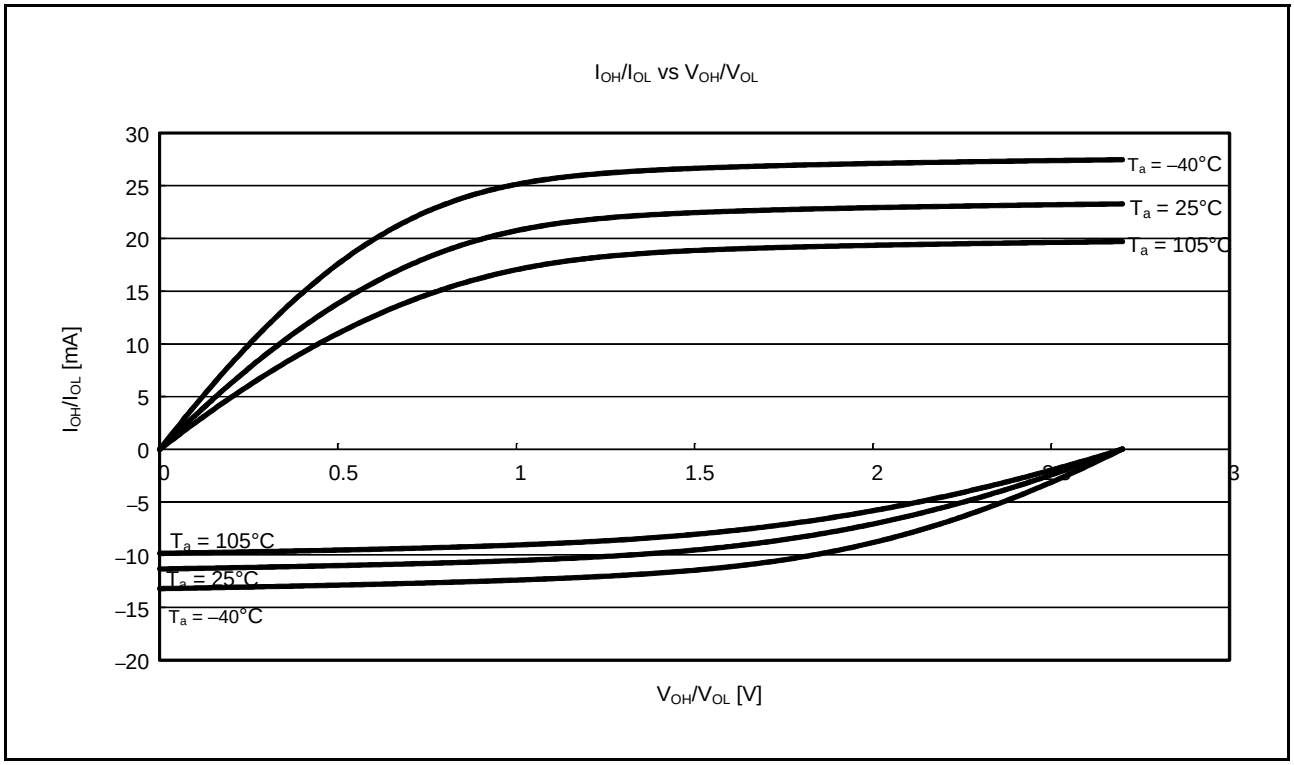


Figure 5.9 V_{OH}/V_{OL} and I_{OH}/I_{OL} Temperature Characteristics of General Ports (Except for the RIIC Output Pin, Ports P40 to P44, P46, Ports PJ6, PJ7) at VCC = 2.7 V (Reference Data)

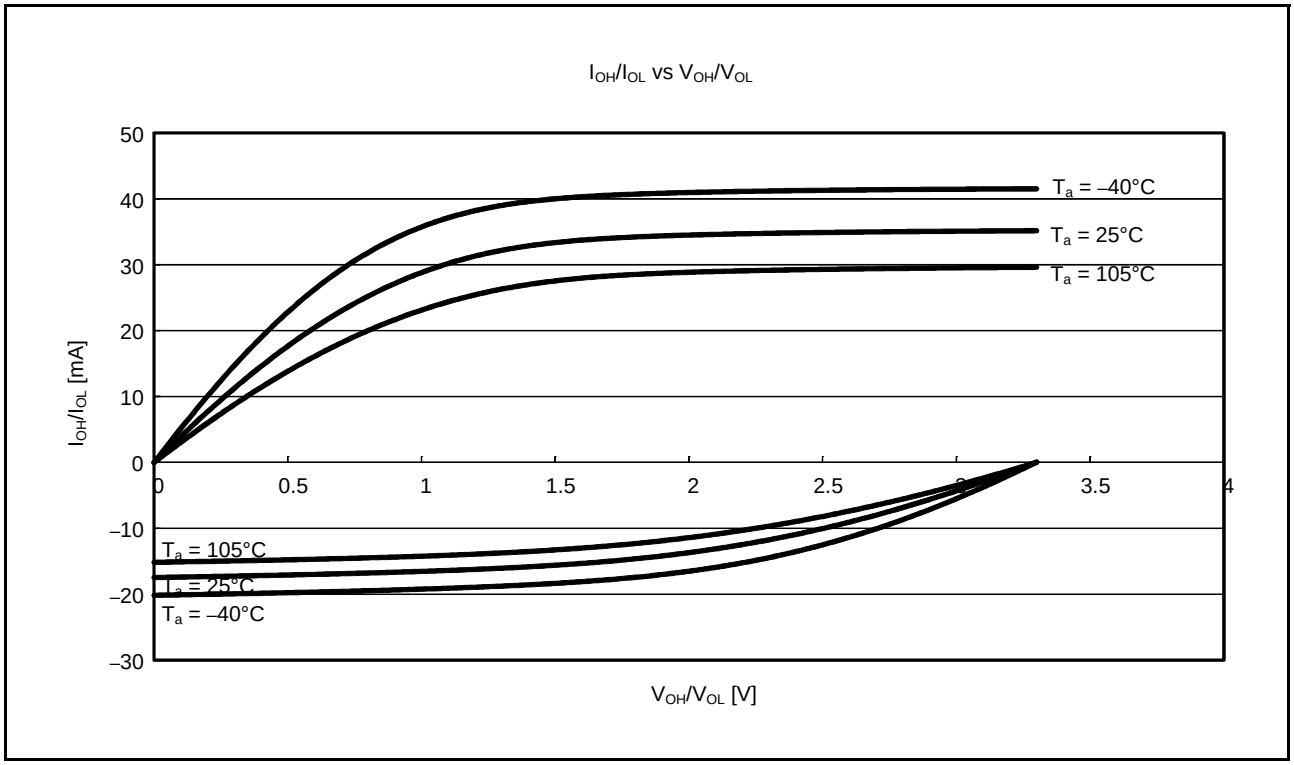


Figure 5.10 V_{OH}/V_{OL} and I_{OH}/I_{OL} Temperature Characteristics of General Ports (Except for the RIIC Output Pin, Ports P40 to P44, P46, Ports PJ6, PJ7) at VCC = 3.3 V (Reference Data)

5.3 AC Characteristics

5.3.1 Clock Timing

Table 5.19 Operation Frequency Value (High-Speed Operating Mode)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	VCC			Unit
			1.8 to 2.4 V	2.4 to 2.7 V	2.7 to 3.6 V	
Maximum operating frequency	System clock (ICLK)	f_{max}	8	16	32	MHz
	FlashIF clock (FCLK)*1, *2		8	16	32	
	Peripheral module clock (PCLKB)		8	16	32	
	Peripheral module clock (PCLKD)*3		8	16	32	

Note 1. The lower-limit frequency of FCLK is 1 MHz during programming or erasing of the flash memory. When using FCLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.
Note 2. The frequency accuracy of FCLK should be ±3.5%. Confirm the frequency accuracy of the clock source.
Note 3. The lower-limit frequency of PCLKD is 4 MHz at 2.4 V or above and 1 MHz at below 2.4 V when the A/D converter is in use.

Table 5.20 Operation Frequency Value (Middle-Speed Operating Mode)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	VCC			Unit
			1.8 to 2.4 V	2.4 to 2.7 V	2.7 to 3.6 V	
Maximum operating frequency	System clock (ICLK)	f_{max}	8	12	12	MHz
	FlashIF clock (FCLK)*1, *2		8	12	12	
	Peripheral module clock (PCLKB)		8	12	12	
	Peripheral module clock (PCLKD)*3		8	12	12	

Note 1. The lower-limit frequency of FCLK is 1 MHz during programming or erasing of the flash memory. When using FCLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.
Note 2. The frequency accuracy of FCLK should be ±3.5%.
Note 3. The lower-limit frequency of PCLKD is 4 MHz at 2.4 V or above and 1 MHz at below 2.4 V when the A/D converter is in use.

Table 5.21 Operation Frequency Value (Low-Speed Operating Mode)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	VCC			Unit
			1.8 to 2.4 V	2.4 to 2.7 V	2.7 to 3.6 V	
Maximum operating frequency	System clock (ICLK)	f_{max}	32.768			kHz
	FlashIF clock (FCLK)*1		32.768			
	Peripheral module clock (PCLKB)		32.768			
	Peripheral module clock (PCLKD)*2		32.768			

Note 1. Programming and erasing the flash memory is impossible.
Note 2. The A/D converter cannot be used.

5.3.2 Reset Timing

Table 5.23 Reset Timing

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
RES# pulse width	At power-on	t_{RESWP}	3	—	—	ms	Figure 5.25
	Other than above	t_{RESW}	30	—	—	μs	Figure 5.26
Wait time after RES# cancellation (at power-on)	At normal startup*1	t_{RESWT}	—	8.5	—	ms	Figure 5.25
	During fast startup time*2	t_{RESWT}	—	560	—	μs	
Wait time after RES# cancellation (during powered-on state)		t_{RESWT}	—	114	—	μs	Figure 5.26
Independent watchdog timer reset period		t_{RESWIW}	—	1	—	IWDT clock cycle	Figure 5.27
Software reset period		t_{RESWSW}	—	1	—	ICLK cycle	
Wait time after independent watchdog timer reset cancellation*3		t_{RESW2}	—	300	—	μs	
Wait time after software reset cancellation		t_{RESW2}	—	168	—	μs	

Note 1. When OFS1.(STUPLVD1REN, FASTSTUP) = 11b.
Note 2. When OFS1.(STUPLVD1REN, FASTSTUP) ≠ 11b.
Note 3. When IWDTCR.CKS[3:0] = 0000b.

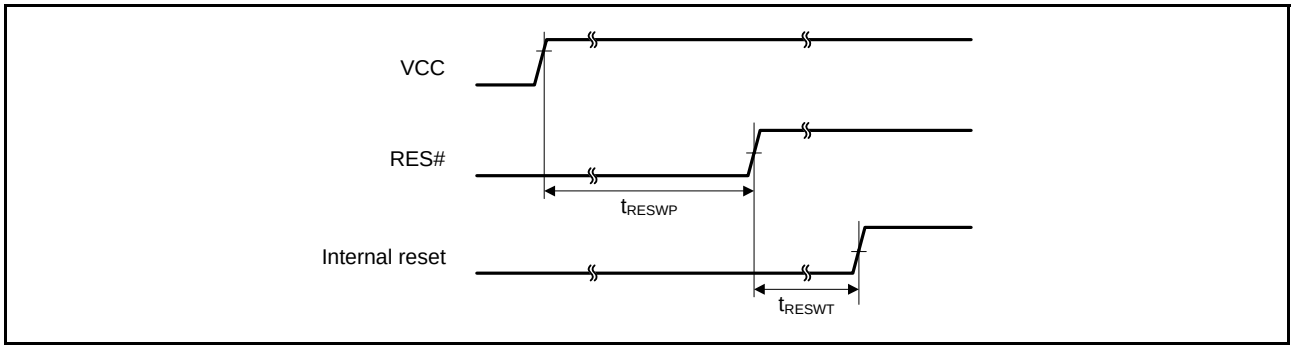


Figure 5.25 Reset Input Timing at Power-On

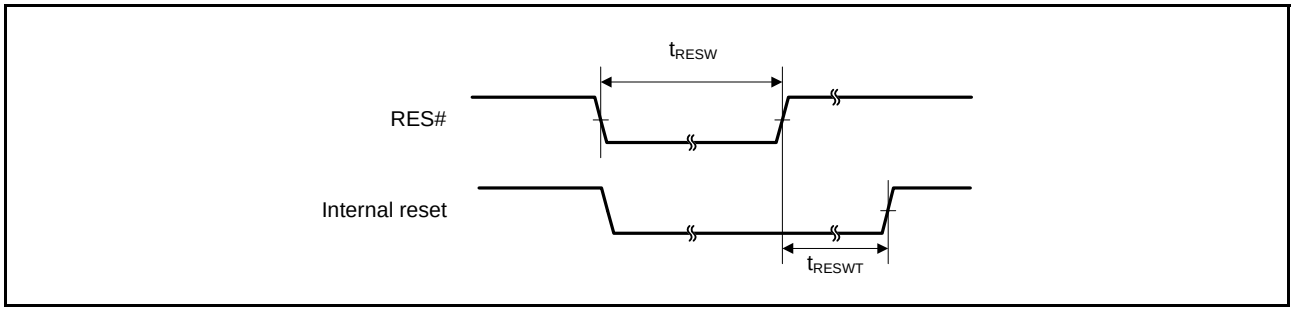


Figure 5.26 Reset Input Timing (1)

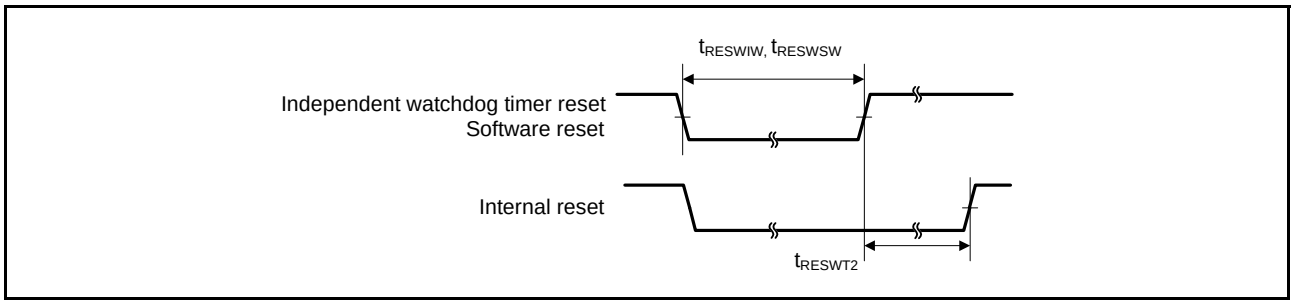


Figure 5.27 Reset Input Timing (2)

Table 5.31 Timing of On-Chip Peripheral Modules (2)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C, C = 30 pF

Item				Symbol	Min.	Max.	Unit	Test Conditions
RSPI	RSPCK clock cycle	Master		t_{SPcyc}	2	4096	t_{Pcyc} *1	Figure 5.39
		Slave			8	4096		
	RSPCK clock high pulse width	Master		t_{SPCKWH}	$(t_{SPcyc} - t_{SPCKr} - t_{SPCKf})/2 - 3$	—	ns	
		Slave			$(t_{SPcyc} - t_{SPCKr} - t_{SPCKf})/2$	—		
	RSPCK clock low pulse width	Master		t_{SPCKWL}	$(t_{SPcyc} - t_{SPCKr} - t_{SPCKf})/2 - 3$	—	ns	
		Slave			$(t_{SPcyc} - t_{SPCKr} - t_{SPCKf})/2$	—		
	RSPCK clock rise/fall time	Output	2.7 V or above	t_{SPCKr}, t_{SPCKf}	—	10	ns	
			1.8 V or above		—	15		
		Input			—	1	µs	
	Data input setup time	Master	2.7 V or above	t_{SU}	10	—	ns	Figure 5.40 to Figure 5.45
			1.8 V or above		30	—		
		Slave			$25 - t_{Pcyc}$	—		
	Data input hold time	Master	RSPCK set to a division ratio other than PCLKB divided by 2	t_H	t_{Pcyc}	—	ns	
			RSPCK set to PCLKB divided by 2	t_{HF}	0	—		
		Slave		t_H	$20 + 2 \times t_{Pcyc}$	—		
	SSL setup time	Master		t_{LEAD}	$–30 + N^{*2} \times t_{SPcyc}$	—	ns	
		Slave			2	—	t_{Pcyc}	
	SSL hold time	Master		t_{LAG}	$–30 + N^{*3} \times t_{SPcyc}$	—	ns	
		Slave			2	—	t_{Pcyc}	
	Data output delay time	Master	2.7 V or above	t_{OD}	—	14	ns	
			1.8 V or above		—	30		
		Slave	2.7 V or above		—	$3 \times t_{Pcyc} + 65$		
			1.8 V or above		—	$3 \times t_{Pcyc} + 105$		
	Data output hold time	Master	2.7 V or above	t_{OH}	0	—	ns	
			1.8 V or above		–20	—		
		Slave			0	—		
	Successive transmission delay time	Master		t_{TD}	$t_{SPcyc} + 2 \times t_{Pcyc}$	$8 \times t_{SPcyc} + 2 \times t_{Pcyc}$	ns	
		Slave			$4 \times t_{Pcyc}$	—		
	MOSI and MISO rise/fall time	Output	2.7 V or above	t_{Dr}, t_{Df}	—	10	ns	
			1.8 V or above		—	20		
		Input			—	1	µs	
	SSL rise/fall time	Output		t_{SSLr}, t_{SSLf}	—	20	ns	
		Input			—	1	µs	
	Slave access time		2.7 V or above	t_{SA}	—	6	t_{Pcyc}	Figure 5.44, Figure 5.45
			1.8 V or above		—	7		
	Slave output release time		2.7 V or above	t_{REL}	—	5	t_{Pcyc}	
			1.8 V or above		—	6		

Note 1. t_{Pcyc}: PCLK cycle
Note 2. N: An integer from 1 to 8 that can be set by the RSPI clock delay register (SPCKD)
Note 3. N: An integer from 1 to 8 that can be set by the RSPI slave select negation delay register (SSLND)

Table 5.32 Timing of On-Chip Peripheral Modules (3)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C, C = 30 pF

Item			Symbol	Min.	Max.	Unit*1	Test Conditions
Simple SPI	SCK clock cycle output (master)		t_{SPcyc}	4	65536	t_{Pcyc}	Figure 5.39
	SCK clock cycle input (slave)			6	65536		
	SCK clock high pulse width		t_{SPCKWH}	0.4	0.6	t_{SPcyc}	
	SCK clock low pulse width		t_{SPCKWL}	0.4	0.6	t_{SPcyc}	
	SCK clock rise/fall time		t_{SPCKr}, t_{SPCKf}	—	20	ns	
	Data input setup time (master)	2.7 V or above	t_{SU}	65	—	ns	Figure 5.40, Figure 5.42
		1.8 V or above		95	—		
	Data input setup time (slave)			40	—		
	Data input hold time		t_H	40	—	ns	
	SS input setup time		t_{LEAD}	3	—	t_{Pcyc}	
	SS input hold time		t_{LAG}	3	—	t_{Pcyc}	
	Data output delay time (master)		t_{OD}	—	40	ns	
	Data output delay time (slave)	2.7 V or above		—	65		
		1.8 V or above		—	85		
	Data output hold time (master)	2.7 V or above	t_{OH}	–10	—	ns	
		1.8 V or above		–20	—		
	Data output hold time (slave)			–10	—		
	Data rise/fall time		t_{Dr}, t_{Df}	—	20	ns	
	SS input rise/fall time		t_{SSLr}, t_{SSLf}	—	20	ns	
	Slave access time		t_{SA}	—	6	t_{Pcyc}	Figure 5.44, Figure 5.45
	Slave output release time		t_{REL}	—	6	t_{Pcyc}	

Note 1. t_{Pcyc}: PCLK cycle

5.4 A/D Conversion Characteristics

Table 5.35 A/D Conversion Characteristics (1)

Conditions: 2.7 V ≤ VCC ≤ 3.6 V, 2.7 V ≤ AVCC0 ≤ 3.6 V, 2.7 V ≤ VREFH0 ≤ AVCC0, VSS = AVSS0 = VREFL0 = 0 V,
T_a = –40 to +105°C

Item		Min.	Typ.	Max.	Unit	Test Conditions
Frequency		4	—	32	MHz	
Resolution		—	—	12	Bit	
Conversion time*1 (Operation at PCLKD = 32 MHz)	Permissible signal source impedance (Max.) = 0.3 kΩ	1.031 (0.313)*2	—	—	µs	High-precision channel ADCSR.ADHSC bit = 1 ADSSTRn.SST[7:0] bits = 09h
		1.375 (0.641)*2	—	—		Normal-precision channel ADCSR.ADHSC bit = 1 ADSSTRn.SST[7:0] bits = 14h
Analog input effective range		0	—	VREFH0	V	
Offset error		—	±0.5	±4.5	LSB	High-precision channel PJ6PFS.ASEL bit = 1 PJ7PFS.ASEL bit = 1
				±6.0	LSB	Other than above
Full-scale error		—	±0.75	±4.5	LSB	High-precision channel PJ6PFS.ASEL bit = 1 PJ7PFS.ASEL bit = 1
				±6.0	LSB	Other than above
Quantization error		—	±0.5	—	LSB	
Absolute accuracy		—	±1.25	±5.0	LSB	High-precision channel PJ6PFS.ASEL bit = 1 PJ7PFS.ASEL bit = 1
				±8.0	LSB	Other than above
DNL differential nonlinearity error		—	±1.0	—	LSB	
INL integral nonlinearity error		—	±1.0	±3.0	LSB	

Note: The characteristics apply when no pin functions other than A/D converter input are used. Absolute accuracy includes quantization errors. Offset error, full-scale error, DNL differential nonlinearity error, and INL integral nonlinearity error do not include quantization errors.

Note 1. The conversion time is the sum of the sampling time and the comparison time. As the test conditions, the number of sampling states is indicated.

Note 2. The value in parentheses indicates the sampling time.

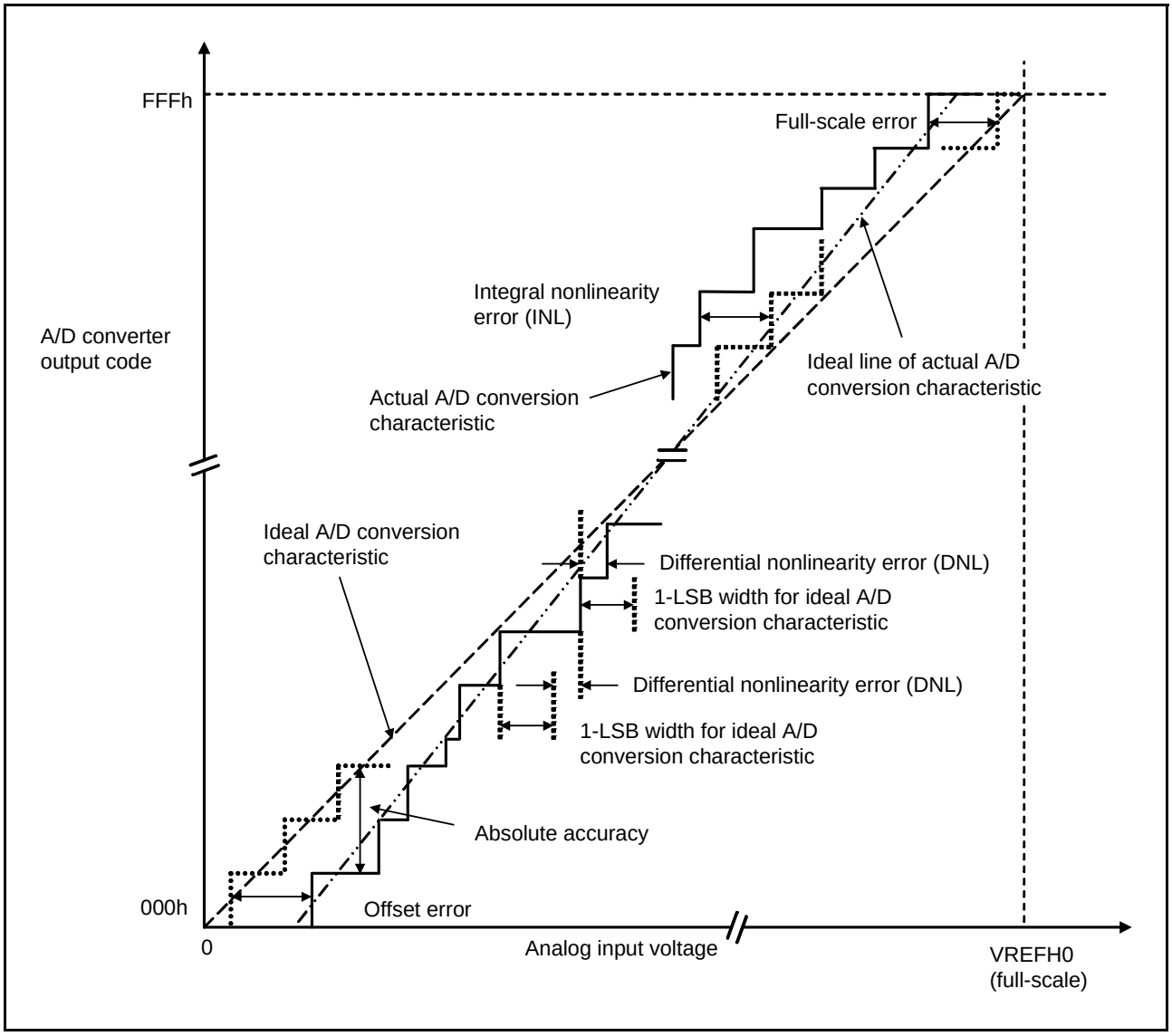


Figure 5.48 Illustration of A/D Converter Characteristic Terms

Absolute accuracy

Absolute accuracy is the difference between output code based on the theoretical A/D conversion characteristics, and the actual A/D conversion result. When measuring absolute accuracy, the voltage at the midpoint of the width of analog input voltage (1-LSB width), that can meet the expectation of outputting an equal code based on the theoretical A/D conversion characteristics, is used as an analog input voltage. For example, if 12-bit resolution is used and if reference voltage (VREFH0 = 3.072 V), then 1-LSB width becomes 0.75 mV, and 0 mV, 0.75 mV, 1.5 mV, ... are used as analog input voltages.

If analog input voltage is 6 mV, absolute accuracy = ±5 LSB means that the actual A/D conversion result is in the range of 003h to 00Dh though an output code, 008h, can be expected from the theoretical A/D conversion characteristics.

Integral nonlinearity error (INL)

Integral nonlinearity error is the maximum deviation between the ideal line when the measured offset and full-scale errors are zeroed, and the actual output code.

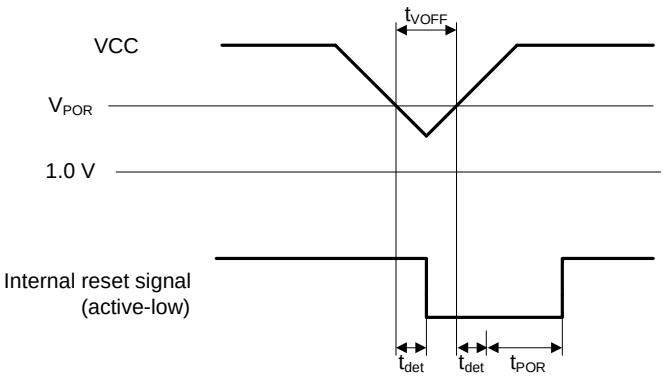
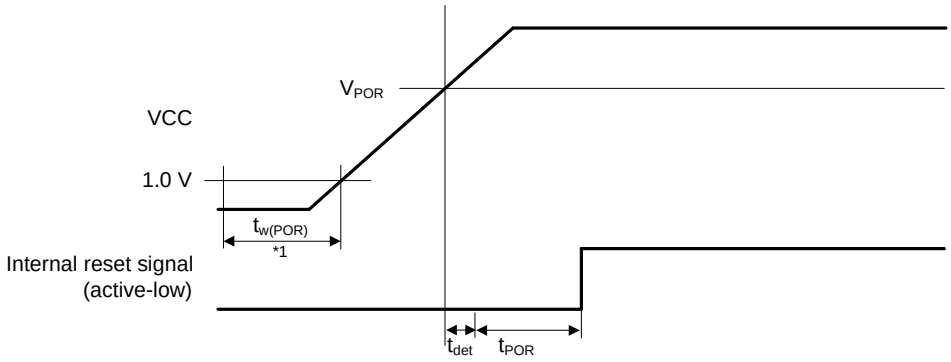


Figure 5.49 Voltage Detection Reset Timing



Note 1. $t_{w(por)}$ is the time required for a power-on reset to be enabled while the external power VCC is being held below the valid voltage (1.0 V).
When VCC turns on, maintain $t_{w(por)}$ for 1.0 ms or more.

Figure 5.50 Power-On Reset Timing

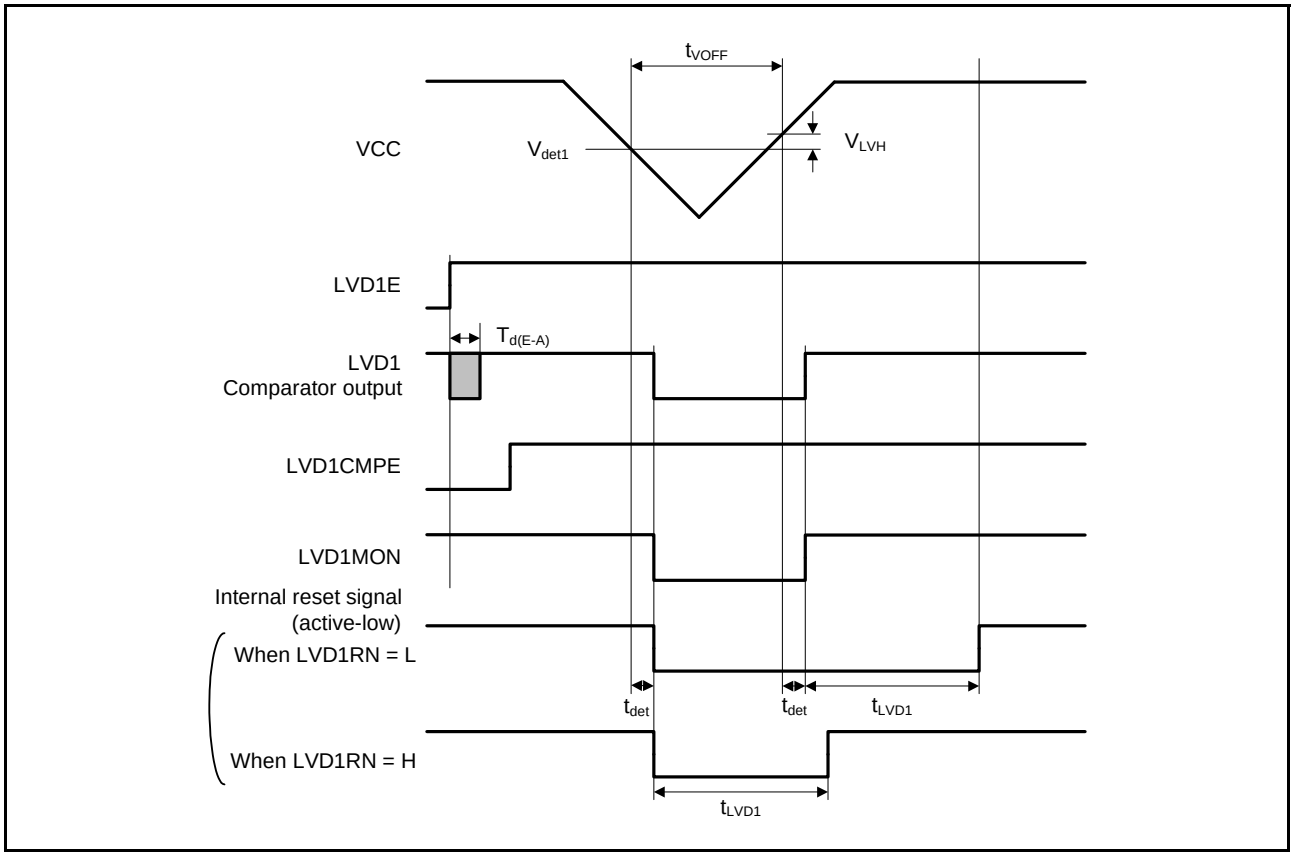


Figure 5.51 Voltage Detection Circuit Timing (V_{det1})

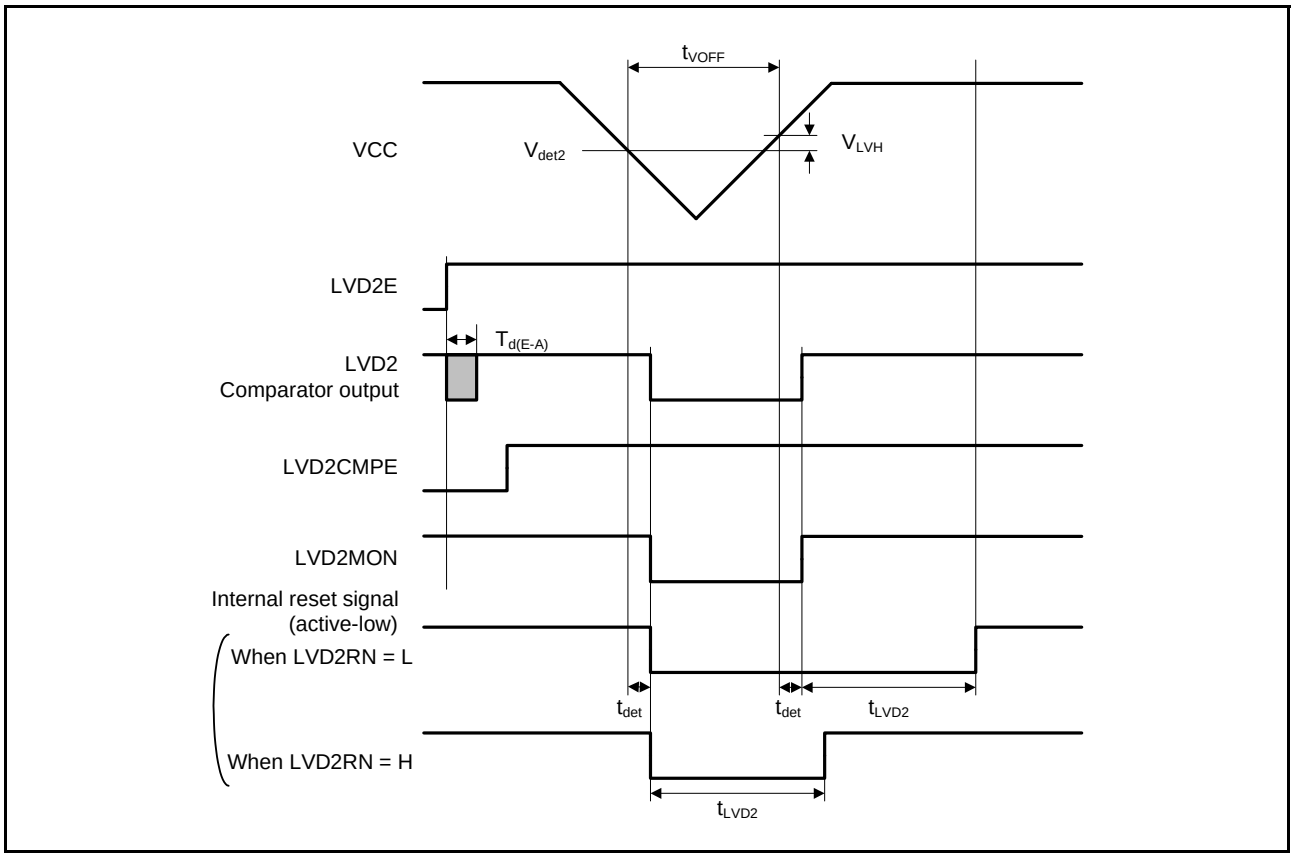


Figure 5.52 Voltage Detection Circuit Timing (V_{det2})

Table 5.46 ROM (Flash Memory for Code Storage) Characteristics (3)

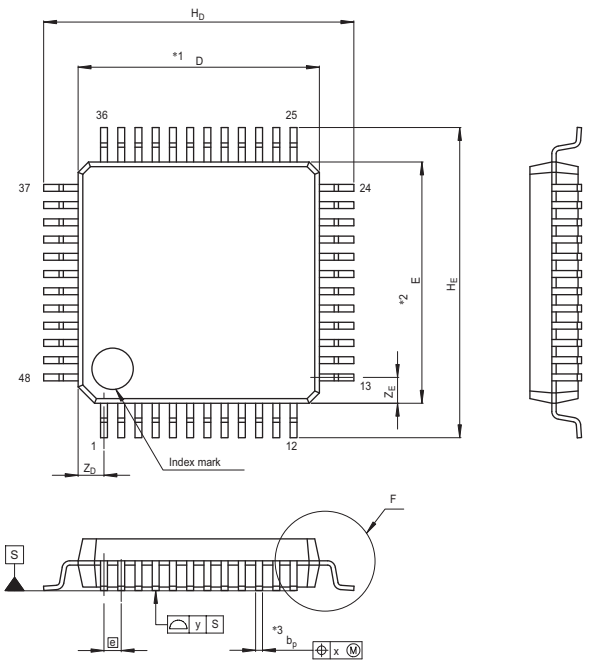
Middle-speed operating mode Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V

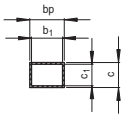
Temperature range for the programming/erasure operation: T_a = –40 to +85°C

Item		Symbol	FCLK = 1 MHz			FCLK = 8 MHz			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	
Programming time	4-byte	t_{P4}	—	143	1330	—	96.8	932	µs
Erasure time	1-Kbyte	t_{E1K}	—	8.3	269	—	5.85	219	ms
	128-Kbyte	t_{E128K}	—	203	464	—	40	260	ms
Blank check time	4-byte	t_{BC4}	—	—	78	—	—	50	µs
	1-Kbyte	t_{BC1K}	—	—	1.61	—	—	0.369	ms
Erase operation forcible stop time		t_{SED}	—	—	33.6	—	—	25.6	µs
Start-up area switching setting time		t_{SAS}	—	13.2	549	—	7.6	445	ms
Access window time		t_{AWS}	—	13.2	549	—	7.6	445	ms
ROM mode transition wait time 1		t_{DIS}	2	—	—	2	—	—	µs
ROM mode transition wait time 2		t_{MS}	3	—	—	3	—	—	µs

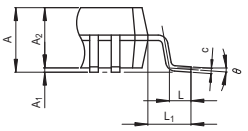
Note: Does not include the time until each operation of the flash memory is started after instructions are executed by software.
Note: The lower-limit frequency of FCLK is 1 MHz during programming or erasing of the flash memory. When using FCLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.
Note: The frequency accuracy of FCLK should be ±3.5%. Confirm the frequency accuracy of the clock source.

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LFQFP48-7x7-0.50	PLQP0048KB-A	48P6Q-A	0.2g





Terminal cross section



Detail F

NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	6.9	7.0	7.1
E	6.9	7.0	7.1
A_2	—	1.4	—
H_D	8.8	9.0	9.2
H_E	8.8	9.0	9.2
A	—	—	1.7
A_1	0	0.1	0.2
b_p	0.17	0.22	0.27
b_1	—	0.20	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.5	—
x	—	—	0.08
y	—	—	0.10
Z_D	—	0.75	—
Z_E	—	0.75	—
L	0.35	0.5	0.65
L_1	—	1.0	—

Figure D 48-Pin LFQFP (PLQP0048KB-A)